

**AMENDMENTS TO THE CLAIMS**

This is a complete and current listing of the claims, marked with status identifiers in parentheses. The following listing of claims will replace all prior versions and listings of claims in the application.

**LISTING OF CLAIMS**

1. (Previously Presented) A molding method for encapsulating both sides of a PCB module, the molding method comprising:
  - preparing a printed circuit board (PCB), the PCB having upper and lower surfaces;
  - preparing a first and a second wafer level package (WLP);
  - mounting the first WLP on the upper surface of the PCB and the second WLP on the lower surface of the PCB, thereby forming the PCB module;
  - placing the PCB module in a mold, the mold including an upper mold and a lower mold, wherein the upper mold includes an upper cavity that encloses the first WLP and an upper gate connected to the upper cavity, and the lower mold includes a lower cavity that encloses the second WLP and a lower gate connected to the lower cavity, and upper and lower inlet blocks defining an inlet connected to the upper gate and the lower gate;
  - forcing a volume of an epoxy mold compound (EMC) through the inlet into the upper and lower gates and through the upper gate into the upper cavity and through the lower gate into the lower cavity whereby the upper cavity and the lower cavity are filled with EMC substantially simultaneously;
  - setting the EMC in the upper and lower cavities, the upper and lower gates and the inlet to form an encapsulated PCB module;
  - separating the encapsulated PCB module from the mold;
  - removing the EMC corresponding to the inlet from the encapsulated PCB module; and

removing the EMC corresponding to the upper gate and the lower gate from the encapsulated PCB module;

wherein removing the EMC corresponding to the upper gate and lower gate includes placing the encapsulated PCB module in a jig; and

mechanically removing the EMC corresponding to the upper gate and the lower gate from the encapsulated PCB module.

2.-4. (Cancelled)

5. (Original) A molding method for encapsulating both sides of a PCB module, the molding method comprising:

preparing a printed circuit board (PCB), the PCB having upper and lower primary surfaces;

attaching an upper film layer to a peripheral portion of the upper primary surface and a lower film layer to a peripheral portion of the lower primary surface;

preparing a first and a second wafer level package (WLP);

mounting the first WLP on the upper primary surface of the PCB and the second WLP on the lower primary surface of the PCB, thereby forming the PCB module;

placing the PCB module in a mold, the mold including an upper mold and a lower mold, wherein the upper mold includes an upper cavity that encloses the first WLP and an upper gate connected to the upper cavity, the upper gate arranged over the upper film layer, and the lower mold includes a lower cavity that encloses the second WLP and a lower gate connected to the lower cavity, the lower gate arranged over the lower film layer, and an inlet block defining an inlet connected to the upper gate and the lower gate;

forcing a volume of an epoxy mold compound (EMC) through the inlet into the upper and lower gates and through the upper gate into the upper cavity and through the lower gate into the lower cavity whereby the upper cavity and the lower cavity are filled with EMC substantially simultaneously;

setting the EMC in the upper and lower cavities, the upper and lower gates and the inlet to form an encapsulated PCB module;  
separating the encapsulated PCB module from the mold; and  
removing the EMC corresponding to the inlet from the encapsulated PCB module.

6. (Original) A molding method for encapsulating both sides of a PCB module according to claim 5, wherein:  
the film layers are adhesive tapes.

7. (Original) A molding method for encapsulating both sides of a PCB module according to claim 5, further comprising:  
removing the EMC corresponding to the upper gate and the lower gate from the encapsulated PCB module by removing the upper and lower film layers.

8. (Original) A molding method for encapsulating both sides of a PCB module according to claim 5, wherein  
removing the EMC corresponding to the inlet includes  
placing the encapsulated PCB module in a jig and  
mechanically removing the EMC corresponding to the inlet from the encapsulated PCB module.

9. (Original) A molding method for encapsulating both sides of a PCB module according to claim 7, wherein  
removing the EMC corresponding to the upper gate and the lower gate includes  
placing the encapsulated PCB module in a jig and  
mechanically removing the upper and lower film layers, thereby removing the EMC corresponding to the upper gate and the lower gate from the encapsulated PCB module.

10. (Original) A molding method for encapsulating both sides of a PCB module according to claim 1, wherein:

the PCB includes a main portion and a peripheral portion, the main portion having a thickness  $T_1$  and the peripheral portion having a thickness  $T_2$ , the thicknesses  $T_1$  and  $T_2$  satisfying the relationship  $T_1 > T_2$ ; and

the upper gate and the lower gate are formed over the peripheral portion.

11. (Original) A molding method for encapsulating both sides of a PCB module according to claim 10, wherein:

the EMC in the upper gate has a thickness  $T_U$  and the EMC in the lower gate has a thickness  $T_L$ , and further wherein  $T_2 + T_U + T_L$  is approximately equal to  $T_1$ .

12. (Currently Amended) A molding method for encapsulating both sides of a PCB module according to claim ~~12~~10, wherein:

$T_U$  and  $T_L$  are substantially equal.

13.-18. (Cancelled)

**\*\*\* END CLAIM LISTING \*\*\***